



### **Single-Event Effects Induced by**

### **Pulsed Laser Irradiation**

### **Dale McMorrow**

Naval Research Laboratory, Washington, DC 20375

### **Stephen Buchner**

QSS Group., Inc., Seabrook, MD 20706





# **Pulsed Picosecond Laser**

- Indispensable tool for SEE characterization
- Above-band gap (single photon)pulsed laser can inject:
  - a well-characterized quantity of charge
  - in a well-defined location
  - at a well-defined time
  - with a well-defined charge-deposition profile
- Several examples





# Single-Photon Absorption SEE Experiment







# Analog Single-Event Transients: Comparison of Pulsed Laser Light and Heavy Ions



Pease, et al., <u>49</u>, Dec. 2002, 3163-3170





### Heavy Ion SET Pulse Width Data: LM124 LET = 53.9 MeV·cm<sup>2</sup>/mg; Voltage Follower





































### Pulsed Laser Data: All Nodes







### Comparison of Heavy Ion and 590 nm Laser SET Pulse Width Data: LM124







### **Backside "Through-Wafer" TPA Illumination**









- Because the laser pulse wavelength is sub-bandgap the material is <u>transparent</u> to the optical pulse
- Carriers are generated by nonlinear absorption at high pulse irradiances by the simultaneous absorption of two photons
- Carriers are highly concentrated in the high irradiance region near the focus of the beam
- Because of the lack of exponential attenuation, carriers can be injected at any depth in the semiconductor material

This permits 3-D mapping and backside illumination





### Carrier generation equation:

$$\frac{dN(r,z)}{dt} = \frac{\alpha I(r,z)}{\hbar \omega} + \frac{\beta_2 I^2(r,z)}{2\hbar \omega}$$

- Because the laser pulse wavelength is sub-bandgap the material is transparent to the optical pulse
- Carriers are generated by nonlinear absorption at high pulse irradiances by the <u>simultaneous absorption of two photons</u>
- Carriers are highly concentrated in the high irradiance region near the focus of the beam
- Because of the lack of exponential attenuation, carriers can be injected at any depth in the semiconductor material
- This permit 3-D mapping and backside illumination







- Because the laser pulse wavelength is sub-bandgap the material is transparent to the optical pulse
- Carriers are generated by nonlinear absorption at high pulse irradiances by the simultaneous absorption of two photons
- Carriers are highly concentrated in the <u>high irradiance region</u> near the focus of the beam
- Because of the lack of exponential attenuation, carriers can be injected at any depth in the semiconductor material
- This permits 3-D mapping and backside illumination







- Because the laser pulse wavelength is sub-bandgap the material is transparent to the optical pulse
- Carriers are generated by nonlinear absorption at high pulse irradiances by the simultaneous absorption of two photons
- Carriers are highly concentrated in the high irradiance region near the focus of the beam
- Because of the lack of exponential attenuation, carriers can be injected at <u>any</u> <u>depth</u> in the semiconductor material
- This permits 3-D mapping and backside illumination







- Because the laser pulse wavelength is sub-bandgap the material is transparent to the optical pulse
- Carriers are generated by nonlinear absorption at high pulse irradiances by the simultaneous absorption of two photons
- Carriers are highly concentrated in the high irradiance region near the focus of the beam
- Because of the lack of exponential attenuation, carriers can be injected at any depth in the semiconductor material
- This permits <u>3-D mapping</u> and <u>backside</u> <u>illumination</u>























# **COMPLEMENTARY TECHINQUE**

- Not intended to replace "conventional" (above band gap) pulsed laser
- Not intended to replace heavy-ion irradiation
- <u>WILL NOT</u> replace these tools
- Is another "Tool" in our "SEE Toolbox"





# Sub-Bandgap, Two-Photon Absorption SEE Experiment







## Three-Dimensional Mapping of SEE Sensitivity (LM124 Q20: General Characteristics)







## Three-Dimensional Mapping of SEE Sensitivity (LM124 Q20: General Characteristics)







### Three-Dimensional Mapping of SEE Sensitivity (LM124 Q20: General Characteristics)





















































































### "Z" Dependence: LM124 Q20 TPA Low Power Measurements





























































### LM124 Q20 TPA SET: "Z" Dependence







### LM124 Q20 TPA SET: "Z" Dependence







### LM124 Q20 TPA SET: "Z" Dependence







### **Backside "Through-Wafer" TPA Illumination**







# **Cross Section of Modern Device**







# Schematic Flip Chip Cross Section







# Backside "Through-Wafer" TPA Illumination LM124 Operational Amplifier







# Backside "Through-Wafer" TPA Illumination LM124 Operational Amplifier







# Backside "Through-Wafer" TPA Illumination LM124 Operational Amplifier







# Backside "Through-Wafer" TPA Illumination SEU in Flip Chip SRAM

- Issues
  - through-wafer imaging
    - InGaAs FPA
  - highly-doped substrate
    - linear loss from free-carrier absorption
    - attenuates IR beam
    - attenuates illumination light
    - wafer <u>thinned</u> to minimize absorption
- <u>Results</u>: SEUs successfully injected in SRAM by TPA at well characterized locations





## Backside "Through-Wafer" TPA Illumination SEU in Flip Chip SRAM Test Structure

# 

### **2D SEU Map**





# Conclusions

- The two-photon absorption method represents a novel approach to SEE evaluation with unique capabilities not exhibited by other techniques
- The present work demonstrates the utility of the nonlinear-optical TPA approach as a method for injecting carriers into the active regions of devices using both top-side and through-wafer, backside irradiation
- The use of backside irradiation eliminates interference from the metallization layers, and circumvents many of the issues associated with testing flip-chip-mounted parts
- The first experimental demonstrations of the through-wafer, backside, two-photon-induced single-event effects technique are presented





# Time-Integrated Charge Collection in a GaAs HBT Device

